

General purpose (Dual digital transistor)

AEC-Q101 Qualified

<For DTr1(NPN)>

Parameter	Value
V _{CEO}	50V
I _C	100mA
R ₁	4.7kΩ

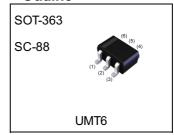
<For DTr2(PNP)>

Parameter	Value
V _{CEO}	-50V
I _C	-100mA
R ₁	4.7kΩ

Features

- 1)Both the DTA143T chip and DTC143T chip in an UMT6 package.
- 2)Mounting possible with UMT3 automatic mounting machines.
- 3)Transistor elements are independent, eliminating interference.
- 4) Mounting cost and area can be cut in half.

Outline



•Inner circuit



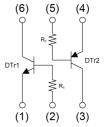
(2) DTr1 Base

(3) DTr2 Collector

(4) DTr2 Emitter

(5) DTr2 Base

(6) DTr1 Collector



Application

INVERTER, INTERFACE, DRIVER

Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
UMD6N FHA	SOT-363 (UMT6)	2021	TR	180	8	3000	D6

• Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	DTr1(NPN)	DTr2(PNP)	Unit
Collector-base voltage	V_{CBO}	50	-50	V
Collector-emitter voltage	V_{CEO}	50	-50	V
Emitter-base voltage	V_{EBO}	5	-5	V
Collector current	I _C	100	-100	mA
Power dissipation	P _D *1*2	² 150		mW/Total
Junction temperature	T _j	150		°C
Range of storage temperature	T _{stg}	-55 to	°C	

● Electrical characteristics (T_a = 25°C) <For DTr1(NPN)>

Development	Cumphed	Canditions	Values			1.1-24
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = 50μA	50	-	-	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 1mA	50	-	-	V
Emitter-base breakdown voltage	BV_{EBO}	I _E = 50μA	5	-	-	V
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	-	500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 5\text{mA}, I_B = 250\mu\text{A}$	-	-	300	mV
DC current gain	h _{FE}	V_{CE} = 5V, I_C = 1mA	100	250	600	-
Input resistance	R ₁	-	3.29	4.7	6.11	kΩ
Transition frequency	f _T *3	$V_{CE} = 10V, I_{E} = -5mA,$ f = 100MHz	-	250	-	MHz

ullet Electrical characteristics (T_a = 25°C) <For DTr2(PNP)>

Doromotor	Cumbal	Conditions	Values			Unit
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic
Collector-base breakdown voltage	BV _{CBO}	I _C = -50μA	-50	-	-	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = -1mA	-50	1	-	V
Emitter-base breakdown voltage	BV_{EBO}	I _E = -50μA	-5	1	1	V
Collector cut-off current	I _{CBO}	V _{CB} = -50V	-	-	-500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = -4V	-	-	-500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -5mA$, $I_B = -0.25mA$	-	-	-300	mV
DC current gain	h _{FE}	$V_{CE} = -5V, I_{C} = -1mA$	100	250	600	-
Input resistance	R ₁	-	3.29	4.7	6.11	kΩ
Transition frequency	f _T *3	$V_{CE} = -10V, I_{E} = 5mA,$ f = 100MHz	-	250	-	MHz

^{*1} Each terminal mounted on a reference land.



^{*2 120}mW per element must not be exceeded.

^{*3} Characteristics of built-in transistor.

● Electrical characteristic curves(T_a = 25°C) < For DTR1(NPN)>

Fig.1 Grounded Emitter Propagation Characteristics

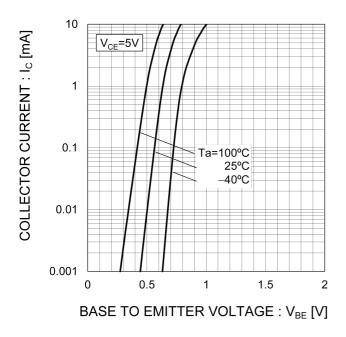


Fig.2 Grounded Emitter Output Characteristics

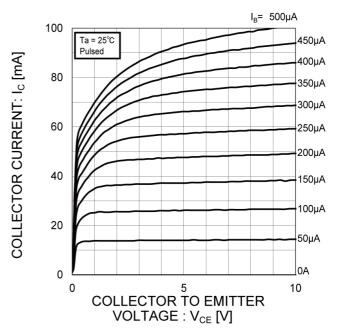


Fig.3 DC Current Gain vs. Collector Current

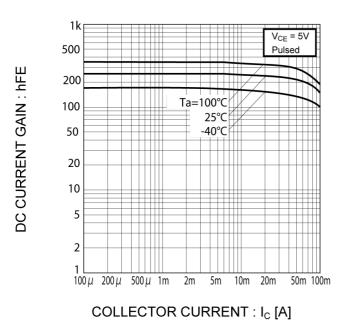
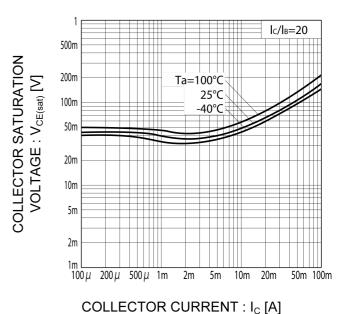


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



● Electrical characteristic curves(T_a = 25°C) < For DTR2(PNP)>

Fig.1 Grounded Emitter Propagation Characteristics

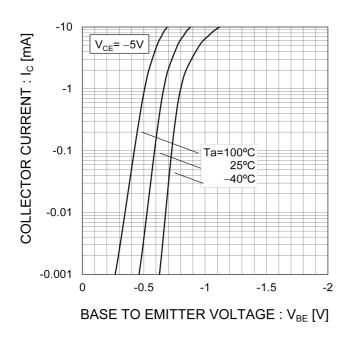


Fig.2 Grounded Emitter Output Characteristics

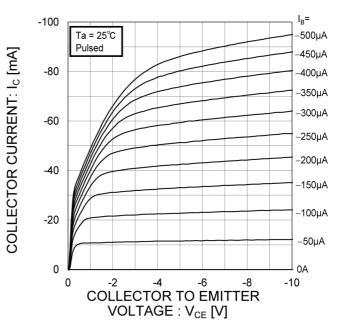


Fig.3 DC Current Gain vs. Collector Current

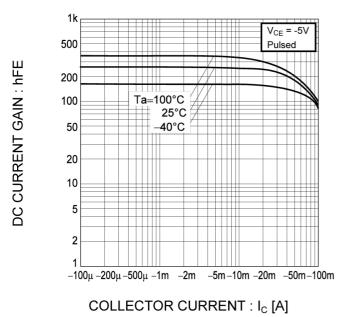
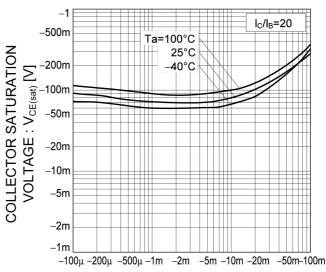
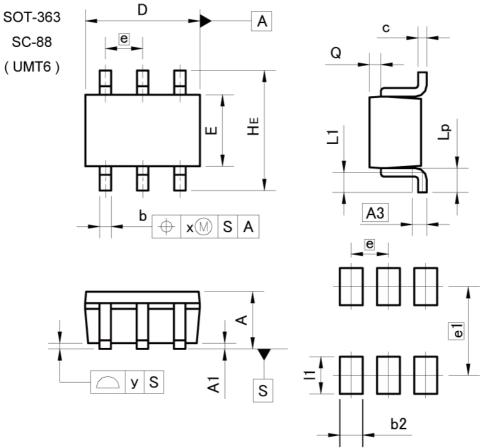


Fig.4 Collector-Emitter Saturation Voltage vs. Collector Current



COLLECTOR CURRENT: Ic [A]

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES				
DIM	MIN	MAX	MIN	MAX				
Α	0.80	1.00	0.031	0.039				
A1	0.00	0.10	0.000	0.004				
A3	0.3	25	0.0	10				
b	0.15	0.30	0.006	0.012				
С	0.10	0.20	0.004	0.008				
D	1.90	2.10	0.075	0.083				
E	1.15	1.35	0.045	0.053				
е	0.65		0.026					
HE	2.00	2.20	0.079	0.087				
L1	0.10	0.40	0.004	0.016				
Lp	0.25	0.55	0.010	0.022				
Q	0.10	0.30	0.004	0.012				
х	Ī	0.10	-	0.004				
У	Î	0.10	-	0.004				
DIM	MILIM	ETERS	INC	HES				
DIM	MIN	MAX	MIN	MAX				
b2	->	0.40	, -	0.016				
e1	1.	55	0.0	61				

Dimension in mm/inches

e1 11



0.026

0.65

Notice

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1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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Ť	JÁPAN	USA	EU	CHINA
	CLASSIII	CLASSIII	CLASS II b	СГУССШ
	CLASSIV	CLASSIII	CLASSIII	CLASSII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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When disposing Products please dispose them properly using an authorized industry waste company.

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